This document describes how to use and configure the TDP158RSBEVM and provides recommendations for system hardware implementation. These recommendations are only guidelines and it is the designer’s responsibility to consider all system characteristics and requirements. Refer to the TDP158 data sheet (SLLSEX2) for technical details such as device operation, terminal description, and so forth.

Contents

1 Overview ........................................................................................................... 2
  1.1 What is the TDP158? ......................................................................................... 2
  1.2 What is the TDP158 EVM? .............................................................................. 2
2 Hardware Description ....................................................................................... 3
  2.1 Video Connectors for TDP158 Ports ............................................................... 3
  2.2 Local I'C Access .......................................................................................... 3
  2.3 Enable and Reset .......................................................................................... 4
  2.4 Power ........................................................................................................... 4
  2.5 Jumper Configuration .................................................................................... 5
  2.6 Component Population Configuration ......................................................... 5
  2.7 USB Interface via TUSB3410 ........................................................................ 6
3 Quick Start Guide .............................................................................................. 6
4 Schematic and Bill of Materials ....................................................................... 7
  4.1 Schematic ..................................................................................................... 7
  4.2 Bill of Materials ............................................................................................ 11
5 Board Layout .................................................................................................... 13
6 Total Phase Aardvark I'C Host Adapter Scripts ................................................. 16
7 References ........................................................................................................ 16

List of Figures

1 TDP158RSBEVM ................................................................................................. 2
2 TDP158RSBEVM Block Diagram ....................................................................... 3
3 TDP158RSBEVM Schematics (1 of 4) - Input Connectors ................................ 7
4 TDP158RSBEVM Schematics (2 of 4) - TDP158RSB Implementation .................... 8
5 TDP158RSBEVM Schematics (3 of 4) - Regulators ............................................. 9
6 TDP158RSBEVM Schematics (4 of 4) - TUSB3410 Implementation .................... 10
7 Layer 1 (Top) .................................................................................................. 13
8 Layer 2 (GND) ................................................................................................ 13
9 Layer 3 (PWR) ................................................................................................ 14
10 Layer 4 (PWR) ................................................................................................ 14
11 Layer 5 (GND) ................................................................................................ 15
12 Layer 6 (Bottom) ............................................................................................ 15

List of Tables

1 Aardvark I'C (J18) Pin-Out ................................................................................ 4
2 TDP158 Target I'C Address .............................................................................. 4
3 SW1 DIP Switch Setting .................................................................................... 5
4 Component Configuration .................................................................................. 5
1 Overview

1.1 What is the TDP158?

The TDP158 is a DisplayPort to Transition Minimized Differential Signal (TMDS) redriver supporting Digital Video Interface (DVI) 1.0 and High Definition Multimedia Interface (HDMI) 1.4b and 2.0 output signals. The TDP158 supports the Dual Mode Standard version 1.1 type 1 and type 2 through the DDC link. The TDP158 supports a data rate of up to 6Gbps per data lane to support UltraHD (4K×2K/60Hz) 8-bits per color high-resolution video and HDTV with 16-bit color depth at 1080p (1920×1080/60Hz).

1.2 What is the TDP158 EVM?

The TDP158 EVM is a PCB created to help customers evaluate the TDP158 device for video applications. This EVM can also be used as a hardware reference design for implementation of the TDP158 in the RSB package. PCB design and layout files can be provided upon request to provide PCB design illustrations of the routing and placement rules. Figure 1 is a picture of the EVM.
1.2.1 What is Included in the TDP158RSBEVM?

The major components of the EVM are as follows:

- TDP158RSB
- Standard DP source connector (receptacle)
- Standard HDMI sink connector (receptacle)
- DC power regulators
- I²C programming interface for external I²C host connection
- USB interface (utility available)

2 Hardware Description

Figure 2 illustrates the EVM block diagram.

2.1 Video Connectors for TDP158 Ports

The EVM has a DP connection for the source and an HDMI connection for the sink. J2 is a standard DP connector (Molex 47272-0001). J4 is a standard HDMI connector (Molex 4715-10001). There is a third video connection on the board for an HDMI source (J1), this function is not supported on the TDP158RSB EVM.

2.2 Local I²C Access

Access to the local I²C signals on the TDP158 is provided via input connector J18. Note that the I²C signal levels should be at 3.3 V when the I²C interface is accessed through the connector.

A standalone external I²C host can be connected via J18 for debug and control purposes. An example of an external I²C Host controller is the Total Phase Aardvark™ I²C/SPI Host Adapter (Total Phase Part#: TP240141). Sample scripts for this I²C Host controller are provided by request.
Table 1. Aardvark I²C (J18) Pin-Out

<table>
<thead>
<tr>
<th>J18 Pin #</th>
<th>Description</th>
<th>J18 Pin #</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>SCL_CTL</td>
<td>2</td>
<td>GND</td>
</tr>
<tr>
<td>3</td>
<td>SDA_CTL</td>
<td>4</td>
<td>NC</td>
</tr>
<tr>
<td>5</td>
<td>NC</td>
<td>6</td>
<td>NC</td>
</tr>
<tr>
<td>7</td>
<td>NC</td>
<td>8</td>
<td>NC</td>
</tr>
<tr>
<td>9</td>
<td>NC</td>
<td>10</td>
<td>GND</td>
</tr>
</tbody>
</table>

Table 2. TDP158 Target I²C Address

<table>
<thead>
<tr>
<th>TDP158 I²C Target Address</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bit 7 (MSB)</td>
</tr>
<tr>
<td>A6</td>
</tr>
</tbody>
</table>

7 Bit Address = 5Eh

NOTE: The target I²C address for the TDP158 can be modified with the EVM jumper settings.

2.3 Enable and Reset

There are three device enable and reset options to use with the EVM.

A. Supervisor circuitry option
   This is the default configuration on the TDP158 EVM. The enable (EN) signal is held low until the power good (PG) from the 3.3-V voltage regulator reaches a stable high-voltage level then is released high.

B. RC timing option
   The C35 external capacitor and internal resistor are used to control the EN ramp time after the device is powered on. The C35 is a DNI (Do Not Install option) by default. The C35 needs to be installed and R70 needs to be uninstalled to enable this option.

C. External control option
   A push button (SW1) is provided for manual control of the EN and OE input of the TDP158.

2.4 Power

A DC power jack (J13) to accept a 5-V wall power adapter is provided on the EVM. The DC power jack (CUI Inc. PJ-202AH) has an inner diameter of 2.1 mm and an outer diameter of 5.5 mm. The tip of the 5-V power supply must be positive. A 5-V power supply of at least 1.5 A that meets the stated requirements can be used to power the TDP158RSBEVM. Power is provided to the EVM when SW1 is set to position 1.

CAUTION

Do not plug in any power source higher than the configured voltage (5 V).

Alternately, it is possible to power the EVM by connecting a USB micro cable to a host and setting SW1 to position 3. Note that this usage may exceed USB compliance requirements for power consumption.
## 2.5 Jumper Configuration

Jumpers are provided to operate the device and EVM in different configurations, see Table 3.

<table>
<thead>
<tr>
<th>DIP SW No</th>
<th>Signal Name</th>
<th>Description</th>
<th>Default Config</th>
</tr>
</thead>
</table>
| J3        | HPD_SNK     | JP 2–3 for external HPD  
                   JP 2–1 for board_5V | JP 2–3 |
| J5        | PRE         | JP 1–2 for 3 db  
                   JP 2–3 for 0 db  
                   When I2C_EN is low | JP 2–3 |
| J6        | SWAP        | JP 1–2 for SWAP  
                   JP 2–3 for Normal  
                   When I2C_EN is low | JP 2–3 |
| J7        | I2C_EN      | JP 1–2 for I2C_EN = High; Puts Device into I2C Control Mode  
                   JP 2–3 for I2C_EN = Low; Puts Device into Pin Strap Mode  
                   Puts Device into Pin Strap Mode | JP 2–3 |
| J8        | TERM        | JP 1–2 for 75–150 Ω  
                   JP 2–3 for 150–300 Ω  
                   NC; no termination | NC  
                   Note: When TMDS_CLOCK_RATIO_STATUS bit = 1, the TDP158 automatically sets source termination at 75 Ω to 150 Ω. |
| J9        | VSADJ       | JP 1–2 for 5.5 kΩ  
                   JP 2–3 for adjustable resistance (6 kΩ)  
                   NC = N/A | JP 2–3  
                   The default value is 6 kΩ on early EVMs (prior to revision B) |
| J10       | EQ1_SEL_A0  | JP 1–2 for:  
                   • I2C Addr bit A0 = 1, when I2C_EN = H  
                   • Fixed EQ at 14 dB @ 3G, when I2C_EN = L  
                   JP 2–3 for:  
                   • I2C Addr bit A0 = 0, when I2C_EN = H  
                   • Fixed EQ at 7.5 dB @ 3G, when I2C_EN = L  
                   NC for Adaptive EQ | NC |
| J11       | EQ2_SEL_A1  | JP 1–2 for:  
                   • I2C Addr bit A0 = 1, when I2C_EN = H  
                   • Fixed EQ at 14 dB @ 3G, when I2C_EN = L  
                   JP 2–3 for:  
                   • I2C Addr bit A0 = 0, when I2C_EN = H  
                   • Fixed EQ at 7.5 dB @ 3G, when I2C_EN = L  
                   NC for Adaptive EQ | NC |
| J12       | SLEW        | JP 1–2 for fast  
                   JP 2–3 for slowest  
                   NC for mid range | NC |

## 2.6 Component Population Configuration

To allow the TDP158 EVM to support both HDMI or DP input, there are many components that need to be removed, placed, or modified depending on the board configuration. Table 4 provides a summary of the component configuration for the TDP158 RSB. In addition, the unused source receptacle can be depopulated.

<table>
<thead>
<tr>
<th>Function</th>
<th>Reference Designator</th>
<th>TDP158</th>
</tr>
</thead>
<tbody>
<tr>
<td>Differential Pair - IN</td>
<td>C16, C17, C18, C19, C20, C21, C22, C23</td>
<td>populated with 0.1 μF</td>
</tr>
<tr>
<td>Differential Pair - HDMI IN</td>
<td>R9, R10, R11, R14, R15, R16, R17, R18</td>
<td>not populated (0 Ω)</td>
</tr>
<tr>
<td>SDA or SCL - HDMI</td>
<td>R12, R13</td>
<td>not populated (2 kΩ)</td>
</tr>
<tr>
<td>Differential Pair - DP</td>
<td>R26, R27, R31, R32, R33, R34, R35, R37</td>
<td>populated with 0 Ω</td>
</tr>
<tr>
<td>SDA, SCL, or HPD - DP</td>
<td>R29, R30</td>
<td>populated with 2 kΩ</td>
</tr>
<tr>
<td>Pullup Differential Pair HDMI IN</td>
<td>R1, R2, R3, R4, R5, R6, R7, R8</td>
<td>populated with 49.9 Ω</td>
</tr>
</tbody>
</table>
2.6.1 DDC Snoop Option

To accommodate systems that do not properly resend DDC commands after HPD goes low, TI has implemented an DDC snoop mode on the TDP158RSB EVM. This mode allows the HPD line to be routed around the TDP158, but remain connected to the TDP158 on the sink side to allow the TDP158 to snoop its state. This snoop mode is disabled, by default, on the TDP158RSB EVMs.

- Pop R22, R23, no pop R19, R20, R12, R13 for HDMI, DDC snoop
- Pop R24, R25, no pop R38, R39, R29, R30 for DP, DDC snoop
- Pop R19, R20, R12, R13, no pop R22, R23 for HDMI, DDC on
- Pop R38, R39, R29, R30, no pop R24, R25 for DP, DDC on

2.6.2 HPD Snoop Option

Not available for the TDP158RSB EVM.

2.7 USB Interface via TUSB3410

Use the following settings for USB interface via TUSB3410:

- J19 must be set to SDA – SDA_USB
- J17 must be set to SCL – SCL_USB
- Attached USB micro cable to J16 and to the host computer
- Start the Eye Scan Tool software. Refer to the EyesScan Tool User’s Guide (SLUUBK2) for details.

3 Quick Start Guide

Use the following steps for quick-start procedures:

1. Apply 5-V power to the EVM, turn on SW1. LED D1 should light up.
2. If using external I²C adapter instead of pin straps, configure the TDP158 at this step.
4. Plug in an HDMI video sink device into J4 (Standard HDMI connector) using a standard HDMI cable.
5. Video output on HDMI sink should be observed.
4 Schematic and Bill of Materials

This section contains the schematics and bill of materials for the EVM.

4.1 Schematic

Figure 3 through Figure 6 illustrates the EVM schematics.

Figure 3. TDP158RSEVM Schematics (1 of 4) - Input Connectors
SDA_CTL and SCL_CTL are configuration inputs when I2C_EN is low. J5 and J6 will set the values of these pins and J17 and J19 should not be populated.
Figure 5. TDP158RSBEVM Schematics (3 of 4) - Regulators
Figure 6. TDP158RSBEVM Schematics (4 of 4) - TUSB3410 Implementation
### 4.2 Bill of Materials

Table 5 lists the EVM BOM.

**Table 5. Bill of Materials**

<table>
<thead>
<tr>
<th>Item</th>
<th>Qty</th>
<th>Reference</th>
<th>Part</th>
<th>PCB Footprint</th>
<th>Manufacturer</th>
<th>Part Number</th>
<th>Pkg</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>2</td>
<td>C1,C51</td>
<td>1 uF</td>
<td>603</td>
<td>Taiyo Yuden</td>
<td>LMK107B705KA-T</td>
<td>603</td>
<td>CAP CER 1UF 10V 10% X7R 0603</td>
</tr>
<tr>
<td>2</td>
<td>5</td>
<td>C38,C41,C43,C46,C50</td>
<td>0.1uF</td>
<td>402</td>
<td>Yageo</td>
<td>CC0402XR56BB104</td>
<td>402</td>
<td>CAP CER 0.1UF 10V 10% X5R 0402</td>
</tr>
<tr>
<td>3</td>
<td>6</td>
<td>C2,C11,C25,C28,C29,C32</td>
<td>10uF</td>
<td>805</td>
<td>TDK</td>
<td>C2012X5R1C06085AC</td>
<td>805</td>
<td>CAP CER 10UF 16V 10% X5R 0805</td>
</tr>
<tr>
<td>4</td>
<td>8</td>
<td>C16,C17,C18,C19,C20,C21,C22,C23</td>
<td>0.1uF</td>
<td>201</td>
<td>TDK</td>
<td>C0603XRJU104M</td>
<td>201</td>
<td>CAP CER .1UF 6.3V X5R 0201</td>
</tr>
<tr>
<td>5</td>
<td>11</td>
<td>C3,C4,C5,C9,C12,C13,C14,C28,C30,C39,C40,C44</td>
<td>0.01uF</td>
<td>402</td>
<td>Murata</td>
<td>GRM1555R71H130KA88D</td>
<td>402</td>
<td>CAP CER 1000PF 50V 10% X7R 0402</td>
</tr>
<tr>
<td>6</td>
<td>4</td>
<td>C6,C10,C14,C33</td>
<td>10 Pf</td>
<td>402</td>
<td>Murata</td>
<td>GRM1555C1H000JA01D</td>
<td>402</td>
<td>CAP CER 10PF 50V 10% X7R 0402</td>
</tr>
<tr>
<td>7</td>
<td>1</td>
<td>C36</td>
<td>18pF</td>
<td>402</td>
<td>AVX</td>
<td>04025A180JAT2A</td>
<td>402</td>
<td>CAP CERM 18PF 50V NP0 0402</td>
</tr>
<tr>
<td>8</td>
<td>1</td>
<td>C37</td>
<td>220pF</td>
<td>402</td>
<td>Taiyo Yuden</td>
<td>UMK105B7221KV-F</td>
<td>402</td>
<td>CAP CER 220PF 50V 10% X7R 0402</td>
</tr>
<tr>
<td>9</td>
<td>1</td>
<td>C24</td>
<td>7343</td>
<td>402</td>
<td>Kemet</td>
<td>T491D227K016AT</td>
<td>7343</td>
<td>CAP TANT 220UF 16V 10% 2917</td>
</tr>
<tr>
<td>10</td>
<td>1</td>
<td>C27</td>
<td>3.3 nF</td>
<td>402</td>
<td>Samsung</td>
<td>CL05B332KB5NNC</td>
<td>402</td>
<td>CAP CER 3300PF 50V 10% X7R 0402</td>
</tr>
<tr>
<td>11</td>
<td>1</td>
<td>C26</td>
<td>22uF</td>
<td>805</td>
<td>Murata</td>
<td>GRM218R60J226ME39L</td>
<td>805</td>
<td>CAP CER 22UF 6.3V 20% X5R 0805</td>
</tr>
<tr>
<td>12</td>
<td>2</td>
<td>C31,C42</td>
<td>2.2uF</td>
<td>805</td>
<td>Taiyo Yuden</td>
<td>EMK212J225KG-T</td>
<td>805</td>
<td>CAP CER 2.2UF 16V 10% X5R 0805</td>
</tr>
<tr>
<td>13</td>
<td>0</td>
<td>C34,C35,R9,R10,R11,R14,R15,R16,R17,R18,R19,R20,R22,R23,R24,R25,R26,R27,R28,R64</td>
<td>DNI</td>
<td>402 / 201</td>
<td>Murata</td>
<td>GRM1555C1H220JA01DF</td>
<td>402</td>
<td>CAP CER 22PF 50V 5% NPO 0402</td>
</tr>
<tr>
<td>14</td>
<td>2</td>
<td>C4S,C48</td>
<td>22pF</td>
<td>402</td>
<td>Murata</td>
<td>GRM1555C1H400JA01D</td>
<td>402</td>
<td>CAP CER 47PF 50V 5% NPO 0420</td>
</tr>
<tr>
<td>15</td>
<td>2</td>
<td>C47,C49</td>
<td>33pF</td>
<td>402</td>
<td>Murata</td>
<td>GRM1555C1H300JA01D</td>
<td>402</td>
<td>CAP CER 33PF 50V 5% NPO 0402</td>
</tr>
<tr>
<td>16</td>
<td>2</td>
<td>C7,C15</td>
<td>4.7pF</td>
<td>402</td>
<td>Murata</td>
<td>GRM1555C1H400JA01DF</td>
<td>402</td>
<td>CAP CER 47PF 50V 5% NPO 0402</td>
</tr>
<tr>
<td>17</td>
<td>1</td>
<td>D1</td>
<td>805</td>
<td>LED Green</td>
<td>Lite On</td>
<td>LTST1717KTD</td>
<td>805</td>
<td>LED GREEN CLEAR THIN 0805 SMD</td>
</tr>
<tr>
<td>18</td>
<td>2</td>
<td>J14,J15</td>
<td>100</td>
<td>402</td>
<td>J14X1M1</td>
<td>961102-6404-AR</td>
<td>402</td>
<td>CONN HEADER VERT SGL 3POS GOLD</td>
</tr>
<tr>
<td>19</td>
<td>11</td>
<td>J3,J5,J6,J7,J8,J9,J10,J11,J12,J17,J19</td>
<td>100</td>
<td>402</td>
<td>J14X1M1</td>
<td>961103-6404-AR</td>
<td>402</td>
<td>CONN HEADER VERT SGL 3POS GOLD</td>
</tr>
<tr>
<td>20</td>
<td>1</td>
<td>J2</td>
<td>805</td>
<td>Display Port</td>
<td>Molex</td>
<td>47272-0001</td>
<td>805</td>
<td>DISPLAYPORT CONN RCPT 20POS UDI R/A SMD</td>
</tr>
</tbody>
</table>
| 21   | 1   | J18        | 100  | 402           | J18X1M1      | N2510-6002-RB | 402 | CONN HEADER 10 POS STRIGHT GOLD /
| 22   | 1   | J13        | 100  | 402           | J13X1M1      | PJ-202AH    | 402 | CONN WRF JACK 2 X5.5MM HIGH CUR |
| 23   | 1   | J16        | 100  | 402           | J16X1M1      | PJ-202AH    | 402 | CONN WRF JACK 2 X5.5MM HIGH CUR |
| 24   | 10  | LP1,LP2,LP3,LP4,LP5,LP6,LP7,LP8,LP9,LP10 | 100 | 402           | J16X1M1      | NJ2510-6002-RB | 402 | CONN HEADER 10 POS STRIGHT GOLD /
<p>| 25   | 1   | L1         | 100  | 402           | L1X1M1       | N1013550-0001LF | 100 | USB MICRO USB MICRO B R/A |
| 26   | 1   | L2         | 100  | 402           | L2X1M1       | N1013550-0001LF | 100 | USB MICRO USB MICRO B R/A |
| 27   | 2   | J1,J4      | 100  | 402           | J16X1M1      | 4715100000 | 100 | USB MICRO USB MICRO B R/A |
| 28   | 8   | R1,R2,R3,R4,R5,R6,R7,R8 | 500 | 402           | R1X1M1       | Molex | 4715100000 | 100 | CONN RCPT 18POS HDMI RT ANG SMD |
| 29   | 5   | R42,R77,R80,R81 | 1K | 402           | R42X1M1      | Panasonic | 4715100000 | 100 | CONN RCPT 18POS HDMI RT ANG SMD |</p>
<table>
<thead>
<tr>
<th>Item</th>
<th>Qty</th>
<th>Reference</th>
<th>Part</th>
<th>PCB Footprint</th>
<th>Manufacturer</th>
<th>Part Number</th>
<th>Pkg</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>30</td>
<td>2</td>
<td>R28,R60</td>
<td>100K</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-070100KL</td>
<td>402</td>
<td>RES SMD 100K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>31</td>
<td>10</td>
<td>R26,R27,R31,R32,R33,R34,R35,R37,R38,R39</td>
<td>0</td>
<td>201</td>
<td>Panasonic</td>
<td>ERJ-1G0R000C</td>
<td>201</td>
<td>RES SMD 0.0 OHM JUMPER 1/20W</td>
</tr>
<tr>
<td>32</td>
<td>6</td>
<td>R29,R30,R40,R41,R83,R84</td>
<td>2K</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-072KL</td>
<td>402</td>
<td>RES SMD 2K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>33</td>
<td>17</td>
<td>R43,R44,R45,R46,R47,R48,R49,R50,R52,R53,R54,R57,R58,R59,R62,R70,R72</td>
<td>0 Ohm</td>
<td>402</td>
<td>Panasonic</td>
<td>ERJ-2G0R000X</td>
<td>402</td>
<td>RES SMD 0.0 OHM JUMPER 1/10W</td>
</tr>
<tr>
<td>34</td>
<td>1</td>
<td>R36</td>
<td>1M</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-071ML</td>
<td>402</td>
<td>RES SMD 1M OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>35</td>
<td>1</td>
<td>R51</td>
<td>5.49K</td>
<td>402</td>
<td>Panasonic</td>
<td>ERJ-2R0F5491X</td>
<td>402</td>
<td>RES SMD 5.49K OHM 1% 1/10W 0402</td>
</tr>
<tr>
<td>36</td>
<td>1</td>
<td>R55</td>
<td>PTVO9</td>
<td>10 POT</td>
<td>THRUHOLE</td>
<td>Bourns</td>
<td>PTVO9A-401SF-B103</td>
<td>THRUHOLE</td>
</tr>
<tr>
<td>37</td>
<td>3</td>
<td>R69,R76,R79</td>
<td>10K</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-07010KL</td>
<td>402</td>
<td>RES SMD 10K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>38</td>
<td>2</td>
<td>R65,R71</td>
<td>4.7K</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-074K7L</td>
<td>402</td>
<td>RES SMD 4.7K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>39</td>
<td>1</td>
<td>R67</td>
<td>499</td>
<td>402</td>
<td>Vishay Dale</td>
<td>CRCW0402499RDHEDP</td>
<td>402</td>
<td>RES SMD 499 OHM 0.5% 1/16W 0402</td>
</tr>
<tr>
<td>40</td>
<td>1</td>
<td>R61</td>
<td>750K</td>
<td>402</td>
<td>Vishay Dale</td>
<td>CRCW0402750KUNED</td>
<td>402</td>
<td>RES SMD 750K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>41</td>
<td>1</td>
<td>R63</td>
<td>240K</td>
<td>402</td>
<td>Vishay Dale</td>
<td>CRCW0402240KUNED</td>
<td>402</td>
<td>RES SMD 240K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>42</td>
<td>1</td>
<td>R66</td>
<td>1.87K</td>
<td>402</td>
<td>Stackpole</td>
<td>RMCF0402FT1K87</td>
<td>402</td>
<td>RES SMD 1.87K OHM 1% 1/16W 0402</td>
</tr>
<tr>
<td>43</td>
<td>1</td>
<td>R68</td>
<td>4.99K</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-074K99L</td>
<td>402</td>
<td>RES SMD 4.99K OHM 1% 1/16W 0402</td>
</tr>
<tr>
<td>44</td>
<td>1</td>
<td>R73</td>
<td>1.5K</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-071K5L</td>
<td>402</td>
<td>RES SMD 1.5K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>45</td>
<td>2</td>
<td>R74,R75</td>
<td>33</td>
<td>201</td>
<td>Yageo</td>
<td>RC0201JR-0733RL</td>
<td>201</td>
<td>RES SMD 33 OHM 5% 1/20W 0201</td>
</tr>
<tr>
<td>46</td>
<td>1</td>
<td>R82</td>
<td>15K</td>
<td>402</td>
<td>Yageo</td>
<td>RC0402JR-0715KL</td>
<td>402</td>
<td>RES SMD 15K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>47</td>
<td>1</td>
<td>R56</td>
<td>47K</td>
<td>402</td>
<td>Rohm</td>
<td>MCR01MRJ4T7</td>
<td>402</td>
<td>RES SMD 47K OHM 5% 1/16W 0402</td>
</tr>
<tr>
<td>48</td>
<td>1</td>
<td>SW2</td>
<td>PB SWITCH</td>
<td>SW_MOM_2NO</td>
<td>OMRON</td>
<td>B3SN-3012P</td>
<td>SW_MOM_2NO</td>
<td>SWITCH TACTILE SPST-NO 0.05A 24V</td>
</tr>
<tr>
<td>49</td>
<td>1</td>
<td>SW1</td>
<td>3POS_SPOT</td>
<td>THRUHOLE_3POS</td>
<td>NIKK Switches</td>
<td>MS13ANW03</td>
<td>THRUHOLE_3POS</td>
<td>SW SLIDE SPDT 6A SILVER STR 125V</td>
</tr>
<tr>
<td>50</td>
<td>1</td>
<td>U1</td>
<td>TDP158R5B</td>
<td>40_RSB</td>
<td>Ti</td>
<td>TDP158RSE</td>
<td>40_RSB</td>
<td>6 Gbps AC Coupled to TMDS™/HDMI™ Redriver</td>
</tr>
<tr>
<td>51</td>
<td>1</td>
<td>U5</td>
<td>TPS3808G300DBVT</td>
<td>6DBV</td>
<td>Ti</td>
<td>TPS3808G300DBVT</td>
<td>6DBV</td>
<td>IC Volt Supervisor 3.0V SOT23-6</td>
</tr>
<tr>
<td>52</td>
<td>1</td>
<td>U2</td>
<td>TPS62150A</td>
<td>RGT16</td>
<td>Ti</td>
<td>TPS62150ANSTT</td>
<td>RGT16</td>
<td>IC REG BUCK SYNC ADJ 1A 16QFN</td>
</tr>
<tr>
<td>53</td>
<td>1</td>
<td>U4</td>
<td>TPS61240</td>
<td>6DRV</td>
<td>Ti</td>
<td>TPS61240DRTV</td>
<td>6DRV</td>
<td>IC REG BOOST SYNC 5V 0.45A 650N</td>
</tr>
<tr>
<td>54</td>
<td>1</td>
<td>U3</td>
<td>TPS74201RGT16</td>
<td>RGT20</td>
<td>Ti</td>
<td>TPS74201RGT16</td>
<td>RGT20</td>
<td>IC REG LDO ADJ 1.5A 20VF</td>
</tr>
<tr>
<td>55</td>
<td>1</td>
<td>U6</td>
<td>TUSB3410</td>
<td>LQFP32</td>
<td>Ti</td>
<td>TUSB3410VF</td>
<td>LQFP-32</td>
<td>IC CONV SERIAL-TO-USB 32-LQFP</td>
</tr>
<tr>
<td>56</td>
<td>1</td>
<td>U7</td>
<td>CAT24C256WI-GT3</td>
<td>8SOIC</td>
<td>ON Semiconductor</td>
<td>CAT24C256WI-GT3</td>
<td>8SOIC</td>
<td>IC EEPROM 256KBIT 400KHZ 8SOIC</td>
</tr>
<tr>
<td>57</td>
<td>1</td>
<td>Y1</td>
<td>12 MHz Crystal</td>
<td>ECX-32</td>
<td>ECS Inc.</td>
<td>ECS-120-20-33-TR</td>
<td>4-SMD</td>
<td>CRYSTAL 12MHZ 20PF SMD</td>
</tr>
<tr>
<td>58</td>
<td>4</td>
<td>EVM Assembly</td>
<td>0.75“ Standoff</td>
<td>4-40 - F-F</td>
<td>Keystone Electronics</td>
<td>2029</td>
<td>OD 0.187&quot;</td>
<td>ROUND STANDOFF 4-40 ALUM 3/4&quot;</td>
</tr>
<tr>
<td>59</td>
<td>4</td>
<td>EVM Assembly</td>
<td>0.25“ Stainless Steel Screws</td>
<td>4-40 Phillips Panhead</td>
<td>Building Fasteners</td>
<td>PMSSS 440 0025 PH</td>
<td>OD 0.187&quot;</td>
<td>MACHIN SCREW PAN PHILLIPS 4-40</td>
</tr>
<tr>
<td>60</td>
<td>9</td>
<td>Shunts</td>
<td>Shunt</td>
<td>SHUNT</td>
<td>JM</td>
<td>968102-0000-DA</td>
<td>SHUNT</td>
<td>SHUNT JUMPER 1&quot; BLACK GOLD</td>
</tr>
<tr>
<td>61</td>
<td>1</td>
<td>PCB</td>
<td>TDP158RSBEVM</td>
<td>ANY</td>
<td>Printed Circuit Board</td>
<td>INT043</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Figure 7 through Figure 12 display the EVM board layouts.

Figure 7. Layer 1 (Top)

Figure 8. Layer 2 (GND)
Figure 9. Layer 3 (PWR)

Figure 10. Layer 4 (PWR)
Figure 11. Layer 5 (GND)

Figure 12. Layer 6 (Bottom)
6 Total Phase Aardvark I2C Host Adapter Scripts

Request the latest scripts from your TI representative.

7 References

1. TDP158 6-Gbps AC-Coupled to TMDS™/HDMI™ Redriver

Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<table>
<thead>
<tr>
<th>Changes from Original (February 2017) to A Revision</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>• Changed the EVM Figure 1 ..........................................................</td>
<td>2</td>
</tr>
<tr>
<td>• Corrected Reference Designators column in Table 4 ..................................................</td>
<td>5</td>
</tr>
<tr>
<td>• Corrected TPD158 column resistor values in Table 4................................................</td>
<td>5</td>
</tr>
<tr>
<td>• Changed the Section 2.6.1 .............................................................</td>
<td>6</td>
</tr>
<tr>
<td>• Changed the Section 2.6.2 .............................................................</td>
<td>6</td>
</tr>
<tr>
<td>• Changed From: TDP158 product preview To: the production datasheet in Section 7 ........</td>
<td>16</td>
</tr>
</tbody>
</table>
1. **Delivery:** TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an “EVM” or “EVMs”) to the User (“User”) in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.

1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductors products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM (“Software”) shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software.

1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.

2. **Limited Warranty and Related Remedies/Disclaimers:**

2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.

2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.

2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.

3. **Regulatory Notices:**

3.1 **United States**

3.1.1 Notice applicable to EVMs not FCC-Approved:

**FCC NOTICE:** This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.

3.1.2 For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:

**CAUTION**

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

**FCC Interference Statement for Class A EVM devices**

**NOTE:** This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.
FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 Notice for EVMs delivered in Japan: Please see http://www.tij.co.jp/lds/lt_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lds/lt_ja/general/eStore/notice_01.page

3.3.2 Notice for Users of EVMs Considered “Radio Frequency Products” in Japan: EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry’s Rule for Enforcement of Radio Law of Japan.
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.
開発キットの中には技術基準適合証明を受けていないものがあります。技術基準適合証明を受けていないものご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。

株式会社 日本テキサス・インスツルメンツ
東京都新宿区西新宿6丁目24番1号

3.3.3 Notice for EVMs for Power Line Communication: Please see http://www.tij.co.jp/labs/ti_ja/general/eStore/notice_02.page

電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。http://www.tij.co.jp/labs/ti_ja_general/eStore/notice_02.page

3.4 European Union

3.4.1 For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

4 EVM Use Restrictions and Warnings:

4.1 EVMs are not for use in functional safety and/or safety critical evaluations, including but not limited to evaluations of life support applications.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 Safety-Related Warnings and Restrictions:

4.3.1 User shall operate the EVM within TI’s recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User’s handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. Accuracy of Information: To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.
6. **Disclaimers:**

6.1 **EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.

6.2 **EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSES OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.

7. **USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.** USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSES AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.

8. **Limitations on Damages and Liability:**

8.1 **General Limitations.** IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS, REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.

8.2 **Specific Limitations.** IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMNITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.

9. **Return Policy:** Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.

10. **Governing Law:** These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2018, Texas Instruments Incorporated
IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ("TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and comliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include, without limitation, TI's standard terms for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm), evaluation modules, and samples (http://www.ti.com/sc/docs/sampterms.htm).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2018, Texas Instruments Incorporated